	Number:	201605260	03			P	CN Date:	6/2/2016	
<b>Fitle</b>	e: Datasheet fo	or SN65DP159	, S	N75DP159					
Cus	tomer Contact:	PCN Manager			D	)ep	ot: Qu	ality Services	
Cha	nge Type:		_						
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<ul> <li>Mechanical Specification</li> <li>Packing/Shipping/Labeling</li> </ul>			$\square$	Test Process		╡	Wafer Fab Materials		
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	cription of Chan			ouncing an information o					
	product datasheet following change Texas INSTRUMENTS	.,		ted as summarized below further details.	ν.		CNGED D450		
	INSTRUMENTS				SUS	F.J2F	SN65DP159, 3-JULY 2015-REV	SN75DP159	
Cha	anges from Revision A	(July 2015) to Revi	sior	В	0220			Page	
	Deleted the VDD_ramp a Changed text "through th Description Changed the HDMI and I Added Note to 11–400-k Changed the note in the	and VCC_ramp MIN ne I <sup>2</sup> C interface" To: DVI value for 1Ah T bps in Table 7 DEV_FUNC_MODE IC_TRAIN_SET sect	valu "thr able E sec	ues in Table 1 ough the I <sup>2</sup> C access on the DDC in 3 ction of Table 7 of Table 8 Change From:	iterfac	:e" i	in DDC Functio	27 nal 32 33 36 37	
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